

## 112 Gbps PAM4, LOW PROFILE HIGH-DENSITY CABLE SYSTEM



NRZ PAM4

56
112
G b p s

## FEATURES & BENEFITS

- Ultra low profile interconnect for placement adjacent to the IC package, under heat sinks or other cooling hardware
- Up to 16 pairs in an incredibly low 4 mm profile
- 112 Gbps PAM4 per lane enabling 25.6 TB aggregate with a path to 51.2 TB
- Si-Fly™ HD is the highest density on-package system with 224 Gbps PAM4 performance, routing signals from the silicon package through Eye Speed® AIR™ ultra performance twinax cable (HPC/HPI). Contact HDR@samtec.com for additional information.
- PCle® 6.0/CXL™ 3.1 capable





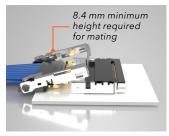




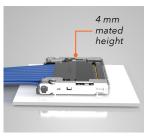


Current

Future







In development: Rugged latching configuration provides a secure connection directly adjacent to the IC package for increased signal integrity performance

## **KEY SPECIFICATIONS (CPC/CPI)**

CABLE	SIGNAL ROUTING	INSULATOR MATERIAL	CONTACT MATERIAL	PLATING
34 AWG ultra low skew twinax	92 Ω & 100 Ω	Black LCP	Copper Alloy	Au over 50 μ" (1.27 μm) Ni

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## 0.6 mm LOW PROFILE CABLE & INTERCONNECT

